⊘TDK Chip Beads

MPZ2012S331AT000

Applications	E Commercial Grade	
Feature	Power Dower Line	
Series	MPZ Series / MPZ2012 Type	
Status	Production	



Size			
Length(L)	2.00mm +/-0.20mm		
Width(W)	1.25mm +/-0.20mm		
Thickness(T)	0.85mm +/-0.20mm		
Recommended Land Pattern (A)	0.80mm Nom.		
Recommended Land Pattern (B)	1.00mm Nom.		
Recommended Land Pattern (C)	1.20mm Nom.		

Electrical Characteristics			
Impedance at 100MHz	330Ω +/-25%		
Rated Current	2.5A		
DC Resistance [Max.]	50mΩ		

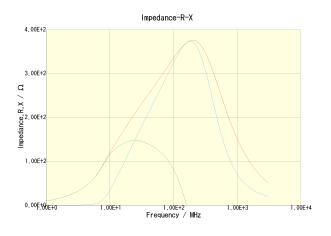
Other				
Operating Temp. Range (Including Self-Temp. Rise)	-55 to 125degC			
Soldering Method	Reflow, Iron Soldering			
AEC Q200	No			
Packing	Punched (Paper)Taping [180mm Reel]			
Package Quantity	4000Pcs Min.			
Weight	0.008g			

•This PDF document was created based on the data listed on the TDK Corporation website.

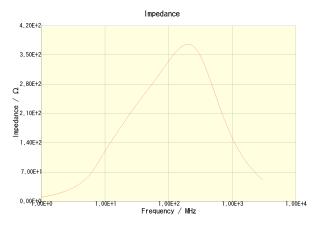
•All specifications are subject to change without notice.

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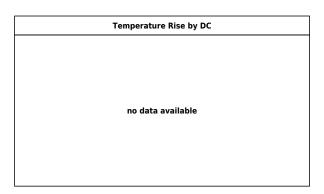
Characteristic Graphs (This is reference data, and does not guarantee the product's characteristics.)

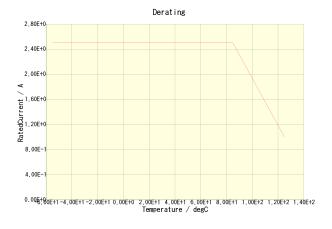


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